

## MOS FIELD EFFECT TRANSISTOR **2SK3360**

### SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

### **DESCRIPTION**

The 2SK3360 is N-Channel MOS Field Effect Transistor designed for high current switching application.

### **ORDERING INFORMATION**

PART NUMBER	PACKAGE		
2SK3360	Isolated TO-220		

### **FEATURES**

- · Low on-state resistance
- $\bigstar$  RDS(on)1 = 30 m $\Omega$  MAX. (VGS = 10 V, ID = 18 A)
- $\bigstar$  RDS(on)2 = 40 m $\Omega$  MAX. (VGS = 4.5 V, ID = 18 A)
- ★ Low Ciss: Ciss = 3200 pF TYP.
  - Built-in gate protection diode
  - Isolated TO-220 package

(Isolated TO-220)



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25$ °C)

	Drain to Source Voltage	VDSS	100	V
	Gate to Source Voltage	VGSS(AC)	±20	V
	Gate to Source Voltage	VGSS(DC)	+20, -10	V
*	Drain Current (DC)	ID(DC)	±35	Α
*	Drain Current (pulse) Note1	D(pulse)	±140	Α
	Total Power Dissipation (Tc = 25°C)	PT	35	W
	Total Power Dissipation (TA = 25°C)	Рт	2.0	W
	Channel Temperature	Tch	150	°C
	Storage Temperature	$T_{stg}$	-55 to +150	°C
*	Single Avalanche Current Note2	<b>I</b> AS	35	Α
*	Single Avalanche Energy Note2	Eas	122	mJ

**Notes 1.** PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1 %

2. Starting T<sub>ch</sub> = 25 °C, R<sub>G</sub> = 25  $\Omega$ , V<sub>GS</sub> = 20 V $\rightarrow$ 0 V

### THERMAL RESISTANCE

Channel to Case	Rth(ch-C)	3.57	°C/W
Channel to Ambient	Rth(ch-A)	62.5	°C/W

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Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

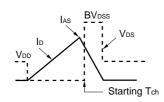


### **★ ELECTRICAL CHARACTERISTICS (TA = 25 °C)**

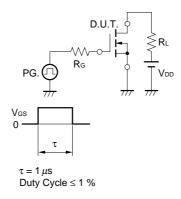
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CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain to Source On-state Resistance	RDS(on)1	V <sub>G</sub> S = 10 V, I <sub>D</sub> = 18 A		20	30	mΩ
	RDS(on)2	Vgs = 4.5 V, lp = 18 A		28	40	mΩ
Gate to Source Cut-off Voltage	V <sub>GS(off)</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 250 μA	1.5	2.0	2.5	V
Forward Transfer Admittance	<b>y</b> fs	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 18 A	13	28		S
Drain Leakage Current	Ipss	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			10	μΑ
Gate to Source Leakage Current	Igss	V <sub>G</sub> S = ±20 V, V <sub>D</sub> S = 0 V			±10	μΑ
Input Capacitance	Ciss	V <sub>DS</sub> = 10 V		3200		pF
Output Capacitance	Coss	V <sub>G</sub> S = 0 V		640		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		360		pF
Turn-on Delay Time	td(on)	ID = 18 A		35		ns
Rise Time	<b>t</b> r	V <sub>GS(on)</sub> = 10 V		220		ns
Turn-off Delay Time	td(off)	V <sub>DD</sub> = 50 V		220		ns
Fall Time	tf	$R_G = 10 \Omega$		190		ns
Total Gate Charge	Q <sub>G</sub>	ID = 35 A		84		nC
Gate to Source Charge	Qgs	V <sub>DD</sub> = 80 V		11		nC
Gate to Drain Charge	Q <sub>GD</sub>	V <sub>GS(on)</sub> = 10 V		31		nC
Body Diode Forward Voltage	V <sub>F(S-D)</sub>	IF = 35 A, VGS = 0 V		0.96		V
Reverse Recovery Time	trr	IF = 35 A, VGS = 0 V		150		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		800		nC

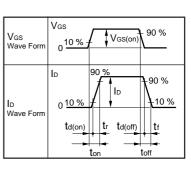
### **TEST CIRCUIT 1 AVALANCHE CAPABILITY**

# $\begin{array}{c|c} D.U.T. \\ \hline PG. \\ \hline \\ V_{GS} = 20 \rightarrow 0 \text{ V} \end{array} \begin{array}{c} D.U.T. \\ \hline \\ \hline \\ \end{array} \begin{array}{c} V_{DD} \\ \hline \\ \end{array}$

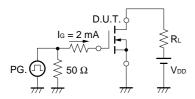


### **TEST CIRCUIT 2 SWITCHING TIME**





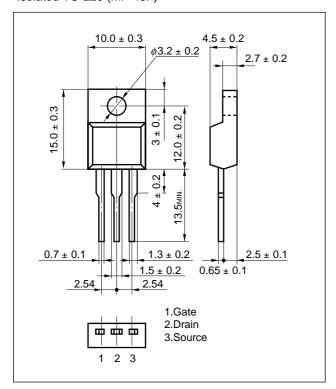
### **TEST CIRCUIT 3 GATE CHARGE**



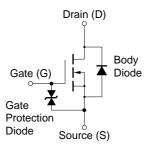


### PACKAGE DRAWING (Unit: mm)

### Isolated TO-220 (MP-45F)



### **EQUIVALENT CIRCUIT**



**Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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